PRODUCT / PROCESS CHANGE NOTIFICATION

1. PCN basic data

1.1 Company	STMicroelectronics International N.V
1.2 PCN No.	ADG/22/13489
1.3 Title of PCN	SPC584BxxE7xx (FC70): Activation of ASE as Assy Plant and KESM as Final Test Plant
1.4 Product Category	see list
1.5 Issue date	2022-06-16

2. PCN Team

2.1 Contact supplier	
2.1.1 Name	ROBERTSON HEATHER
2.1.2 Phone	+1 8475853058
2.1.3 Email	heather.robertson@st.com
2.2 Change responsibility	
2.2.1 Product Manager	Luca RODESCHINI
2.1.2 Marketing Manager	Matteo MOIOLI
2.1.3 Quality Manager	Alberto MERVIC

3. Change

3.1 Category	**3.2 Type of change**	**3.3 Manufacturing Location**
Transfer	Line transfer for a full process or process brick (process step, control plan, recipes) from one site to another site: Assembly site (SOP 2617)	Subcon ASE (Taiwan) and KESM (Malaysia) - Receiving Plants

4. Description of change

	Old	**New**
4.1 Description	Assembly and Final Testing Malta	Assembly Malta and ASE Final Testing Malta and KESM
4.2 Anticipated Impact on form,fit, function, quality, reliability or processability?	No Impact	

5. Reason / motivation for change

5.1 Motivation	Capacity Increase
5.2 Customer Benefit	CAPACITY INCREASE

6. Marking of parts / traceability of change

6.1 Description	Dedicated Finished Good Codes

7. Timing / schedule

7.1 Date of qualification results	2022-12-31
7.2 Intended start of delivery	2023-01-31
7.3 Qualification sample available?	Upon Request

8. Qualification / Validation

8.1 Description			
8.2 Qualification report and qualification results	In progress	**Issue Date**	

9. Attachments (additional documentations)

13489 Public product.pdf
13489 Details.pdf

10. Affected parts		
10. 1 Current		10.2 New (if applicable)
10.1.1 Customer Part No	10.1.2 Supplier Part No	10.1.2 Supplier Part No
	SPC584B70E7NG00X	

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PRODUCT/PROCESS CHANGE NOTIFICATION

TITLE	**SPC584BxxE7xx (FC70): Activation of ASE as Assy Plant and KESM as Final Test Plan**
IMPACTED PRODUCTS	TQFP-176 24x24x1.4 Exposed Pad package: - FC70 – Chorus 2M Crolles Diffusion Plant
MANUFACT. STEP	Assembly, Final Test, Burn In & Finishing
INVOLVED PLANT	Subcontractor ASE – Taiwan Subcontractor KESM – Malaysia
CHANGE REASON	Service – Dual source & Capacity Improvement. Expansion of current assembly and testing capacity (volumes increase) and flexible/secure production asset – dual sourcing strategy.
CHANGE DESCRIPTION	Activation of ASE and KESM as additional BE Assembly and testing plants
TRACEABILITY	Dedicated Finished Good Code
VALIDATION	According to ZVEI (AEC-Q100/Q006) recommendations, items: - SEM-PA-18 (*Move all or part of production to a different assembly site*) - SEM-TF-01 (*Move all or parts of electrical wafer test and/or final test to a different site)*
CURRENT PRODUCTS	Current products assembly and testing will be transferred to ASE and KESM. ST assembly and testing plants will remain active as alternative solution.
REPORTS	Transfer validation is presently in progress. Transfer validation report will be available within Q4 - 2022
IMPLEMENTATION	The Start of Production is foreseen for Q1 - 2023

Public Products List

Publict Products are off the shelf products. They are not dedicated to specific customers, they are available through ST Sales team, or Distributors, and visible on ST.com

PCN Title : SPC584BxxE7xx (FC70): Activation of ASE as Assy Plant and KESM as Final Test Plant

PCN Reference : ADG/22/13489

Subject : Public Products List

Dear Customer,

Please find below the Standard Public Products List impacted by the change.

SPC584B64E7EDC0X	**SPC584B64E7EDC0Y**	**SPC584B70E7NH00X**
SPC584B70E7EHC0X	**SPC584B70E7NG00X**	**SPC584B70E7NMC0X**

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